

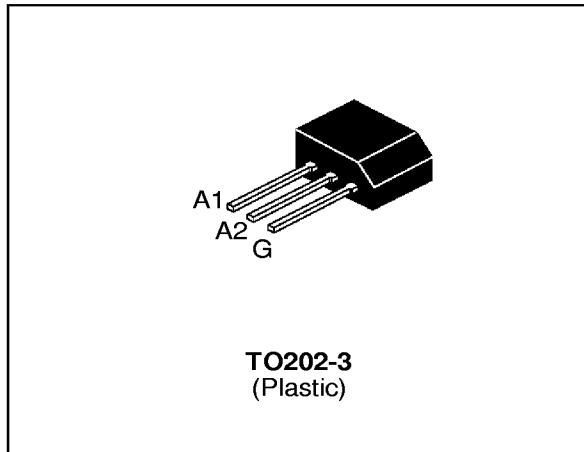
## SENSITIVE GATE TRIACS

### FEATURES

- $I_{T(RMS)} = 4A$
- $V_{DRM} = 400V$  to  $800V$
- $I_{GT} \leq 3mA$  to  $\leq 25mA$

### DESCRIPTION

The Z04xxx series of triacs uses a high performance TOP GLASS PNPN technology. These parts are intended for general purpose applications where high gate sensitivity or high switching performances are required (like touch dimmers, fan, electrovalue control,...).



### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
$I_{T(RMS)}$	RMS on-state current (360° conduction angle)	$T_c = 75^\circ C$	4
		$T_a = 25^\circ C$	0.95
$I_{TSM}$	Non repetitive surge peak on-state current ( $T_j$ initial = $25^\circ C$ )	$t_p = 8.3$ ms	22
		$t_p = 10$ ms	20
$I^2t$	$I^2t$ Value for fusing	$t_p = 10$ ms	$A^2s$
$dl/dt$	Critical rate of rise of on-state current $I_G = 50$ mA $di/dt = 0.1$ A/ $\mu$ s.	Repetitive $F = 50$ Hz	$A/\mu$ s
		Non Repetitive	50
$T_{stg}$ $T_j$	Storage and operating junction temperature range	- 40, + 150 - 40, + 125	°C
$T_I$	Maximum lead temperature for soldering during 10s at 4.5mm from case	260	°C

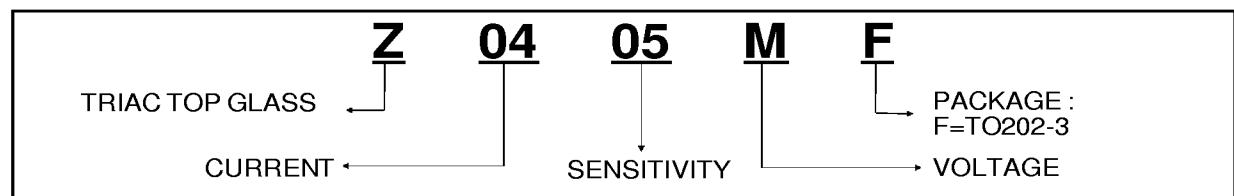
Symbol	Parameter	Voltage			Unit
		D	M	N	
$V_{DRM}$ $V_{RRM}$	Repetitive peak off-state voltage $T_j = 125^\circ C$	400	600	800	V

**Z04xxxF****THERMAL RESISTANCES**

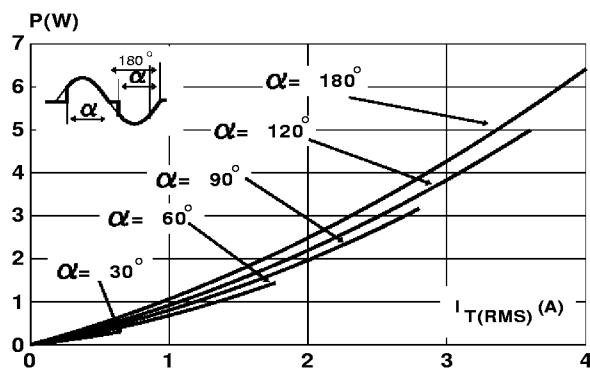
Symbol	Parameter	Value	Unit
R <sub>th(j-a)</sub>	Junction to ambient	100	°C/W
R <sub>th(j-c)</sub>	Junction to case for D.C	10	°C/W
R <sub>th(j-c)</sub>	Junction to case for A.C 360° conduction angle (F=50Hz)	7.5	°C/W

**GATE CHARACTERISTICS**P<sub>G (AV)</sub> = 0.2 W max. P<sub>GM</sub> = 3 W max. (t<sub>p</sub> = 20 μs) I<sub>GM</sub> = 1.2 A max. (t<sub>p</sub> = 20 μs)V<sub>GD</sub> = 0.2V min. (V<sub>D</sub>=V<sub>DRM</sub> R<sub>L</sub>=3.3kΩ T<sub>j</sub>=125°C)**ELECTRICAL CHARACTERISTICS**

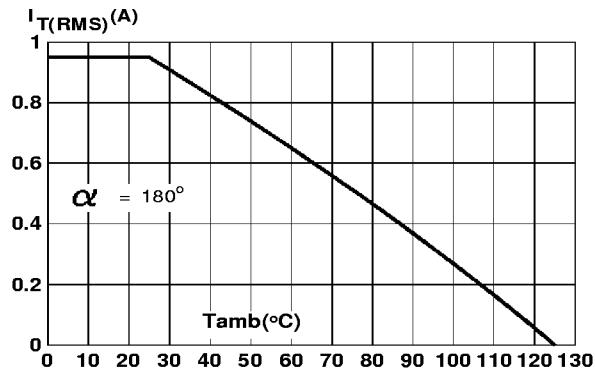
Symbol	Test Conditions	Quadrant		Sensitivity				Unit	
				02	05	09	10		
I <sub>GT</sub>	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	T <sub>j</sub> =25°C	I-II-III-IV	MAX	3	5	10	25	mA
V <sub>GT</sub>	V <sub>D</sub> =12V (DC) R <sub>L</sub> =33Ω	T <sub>j</sub> =25°C	I-II-III-IV	MAX	1.5				V
I <sub>H</sub> *	I <sub>T</sub> = 50 mA Gate open	T <sub>j</sub> = 25°C		MAX	3	5	10	25	mA
I <sub>L</sub>	I <sub>G</sub> = 1.2 I <sub>GT</sub>	T <sub>j</sub> = 25°C	I-III-IV	MAX	6	10	15	25	mA
			II	MAX	12	15	25	50	
V <sub>TM</sub> *	I <sub>TM</sub> = 5.5A t <sub>p</sub> =380μs	T <sub>j</sub> = 25°C		MAX	2				V
I <sub>DRM</sub> I <sub>RRM</sub>	V <sub>D</sub> = V <sub>DRM</sub> V <sub>R</sub> = V <sub>RRM</sub>	T <sub>j</sub> = 25°C		MAX	5				μA
		T <sub>j</sub> = 110°C		MAX	200				
dV/dt*	V <sub>D</sub> =67%V <sub>DRM</sub> Gate open	T <sub>j</sub> = 110°C		MIN	10	20	100	200	V/μs
(dV/dt)c*	(dI/dt)c = 1.3 A/ms	T <sub>j</sub> = 110°C		MIN	0.5	1	2		V/μs
	(dI/dt)c = 1.8 A/ms	T <sub>j</sub> = 110°C		MIN				5	V/μs

\* For either polarity of electrode A<sub>2</sub> voltage with reference to electrode A<sub>1</sub>**ORDERING INFORMATION**

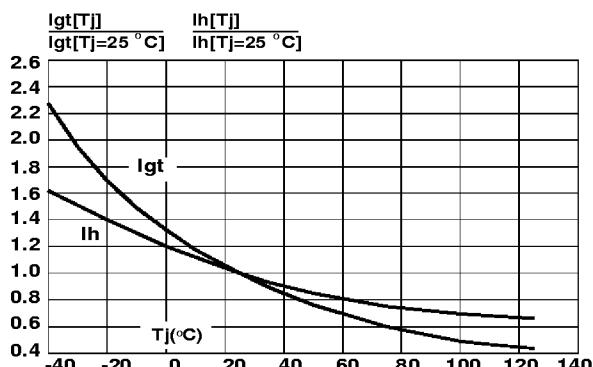
**Fig.1 :** Maximum RMS power dissipation versus RMS on-state current.



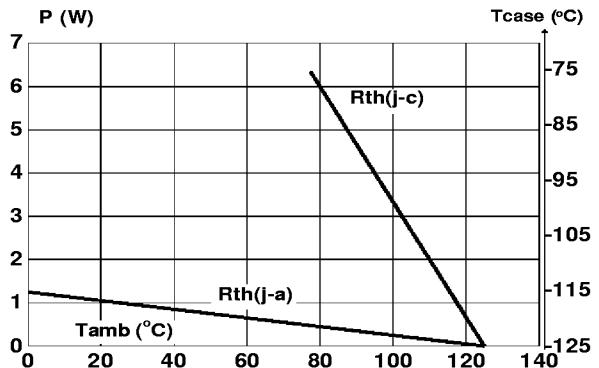
**Fig.3 :** RMS on-state current versus case temperature.



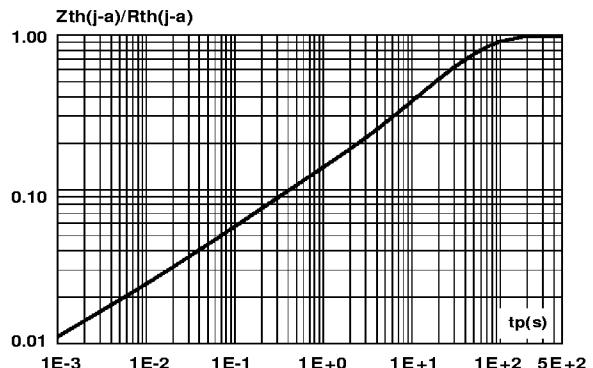
**Fig.5 :** Relative variation of gate trigger current and holding current versus junction temperature.



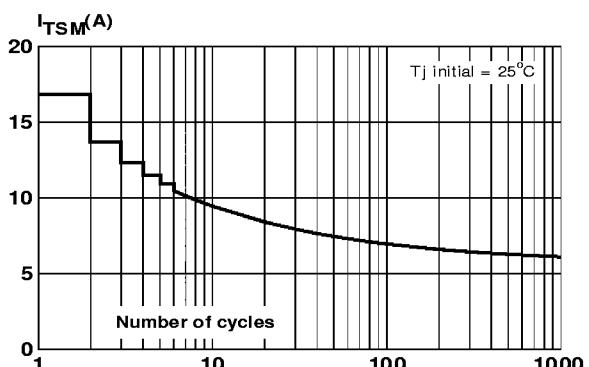
**Fig.2 :** Correlation between maximum RMS power dissipation and maximum allowable temperature (Tamb and Tcase).



**Fig.4 :** Relative variation of thermal impedance junction to ambient versus pulse duration.

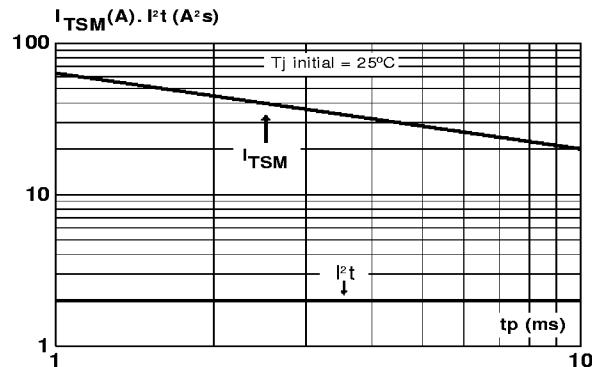


**Fig.6 :** Non repetitive surge peak on-state current versus number of cycles.

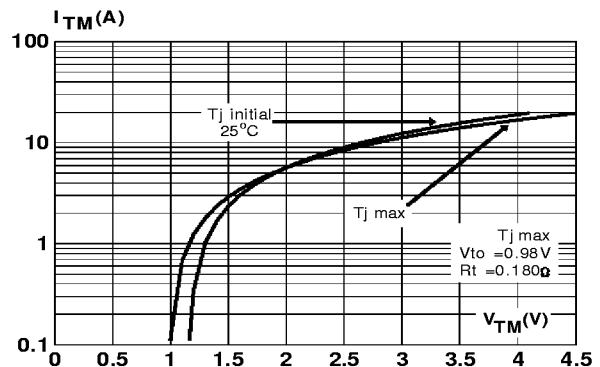


## Z04xxxF

**Fig.7 :** Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t_p \leq 10\text{ms}$ , and corresponding value of  $I^2t$ .



**Fig.8 :** On-state characteristics (maximum values).



## PACKAGE MECHANICAL DATA TO202-3 (Plastic)

REF.	DIMENSIONS			
	Millimeters		Inches	
	Typ.	Max.	Typ.	Max.
A		10.1		0.398
C	7.3		0.287	
D	10.5		0.413	
E	7.4		0.290	
F		1.5		0.059
H	0.51		0.020	
J	1.5		0.059	
M	4.5		0.177	
N		5.3		0.209
N1	2.54		0.100	
O		1.4		0.055
P		0.7		0.028

Marking : type number

Weight : 1 g

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